

# FDS6670AS

## 30V N-Channel PowerTrench® SyncFET™

### General Description

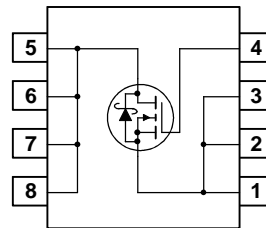
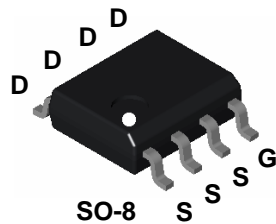
The FDS6670AS is designed to replace a single SO-8 MOSFET and Schottky diode in synchronous DC:DC power supplies. This 30V MOSFET is designed to maximize power conversion efficiency, providing a low  $R_{DS(ON)}$  and low gate charge. The FDS6670AS includes an integrated Schottky diode using Fairchild's monolithic SyncFET technology.

### Applications

- DC/DC converter
- Low side notebook

### Features

- 13.5 A, 30 V.  $R_{DS(ON)}$  max= 9.0 m $\Omega$  @  $V_{GS} = 10$  V  
 $R_{DS(ON)}$  max= 11.5 m $\Omega$  @  $V_{GS} = 4.5$  V
- Includes SyncFET Schottky body diode
- Low gate charge (27nC typical)
- High performance trench technology for extremely low  $R_{DS(ON)}$  and fast switching
- High power and current handling capability



### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain-Source Voltage	30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous (Note 1a)	13.5	A
	– Pulsed	50	
$P_D$	Power Dissipation for Single Operation (Note 1a), (Note 1b), (Note 1c)	2.5	W
		1.2	
		1	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	50	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	25	$^\circ\text{C}/\text{W}$

### Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDS6670AS	FDS6670AS	13"	12mm	2500 units
FDS6670AS	FDS6670AS_NL (Note 4)	13"	12mm	2500 units

**Electrical Characteristics** $T_A = 25^\circ\text{C}$  unless otherwise noted

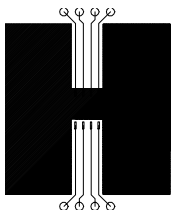
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain–Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 1\text{ mA}$ , Referenced to $25^\circ\text{C}$		31		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$			500	$\mu\text{A}$
$I_{GSS}$	Gate–Body Leakage	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$			$\pm 100$	nA
<b>On Characteristics (Note 2)</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 1\text{ mA}$	1	1.7	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 1\text{ mA}$ , Referenced to $25^\circ\text{C}$		–3.3		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain–Source On–Resistance	$V_{GS} = 10\text{ V}, I_D = 13.5\text{ A}$ $V_{GS} = 4.5\text{ V}, I_D = 11.2\text{ A}$ $V_{GS} = 10\text{ V}, I_D = 13.5\text{ A}, T_J = 125^\circ\text{C}$		7.5 9 10	9 11.5 12.5	m $\Omega$
$I_{D(on)}$	On–State Drain Current	$V_{GS} = 10\text{ V}, V_{DS} = 5\text{ V}$	50			A
$g_{FS}$	Forward Transconductance	$V_{DS} = 10\text{ V}, I_D = 13.5\text{ A}$		66		S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V},$		1540		pF
$C_{oss}$	Output Capacitance	$f = 1.0\text{ MHz}$		440		pF
$C_{rss}$	Reverse Transfer Capacitance			160		pF
	Gate Resistance	$V_{GS} = 15\text{ mV}, f = 1.0\text{ MHz}$		2.1		
<b>Switching Characteristics (Note 2)</b>						
$t_{d(on)}$	Turn–On Delay Time	$V_{DS} = 15\text{ V}, I_D = 1\text{ A},$ $V_{GS} = 10\text{ V}, R_{GEN} = 6\ \Omega$		10	20	ns
$t_r$	Turn–On Rise Time			5	10	ns
$t_{d(off)}$	Turn–Off Delay Time			27	44	ns
$t_f$	Turn–Off Fall Time			18	32	ns
$t_{d(on)}$	Turn–On Delay Time	$V_{DS} = 15\text{ V}, I_D = 1\text{ A},$ $V_{GS} = 4.5\text{ V}, R_{GEN} = 6\ \Omega$		13	23	ns
$t_r$	Turn–On Rise Time			15	27	ns
$t_{d(off)}$	Turn–Off Delay Time			24	38	ns
$t_f$	Turn–Off Fall Time			13	23	ns
$Q_{g(TOT)}$	Total Gate Charge at $V_{GS}=10\text{V}$	$V_{DD} = 15\text{ V}, I_D = 13.5\text{ A},$		27	38	nC
$Q_g$	Total Gate Charge at $V_{GS}=5\text{V}$			16	22	nC
$Q_{gs}$	Gate–Source Charge			4.2		nC
$Q_{gd}$	Gate–Drain Charge			5.1		nC

## Electrical Characteristics

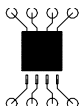
$T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Drain–Source Diode Characteristics and Maximum Ratings</b>						
$V_{SD}$	Drain–Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 3.5\text{ A}$ (Note 2) $V_{GS} = 0\text{ V}, I_S = 7\text{ A}$ (Note 2)		0.5 0.6	0.7	V
$t_{rr}$	Diode Reverse Recovery Time	$I_F = 13.5\text{ A},$ $d_F/d_t = 300\text{ A}/\mu\text{s}$ (Note 3)		20		nS
$Q_{rr}$	Diode Reverse Recovery Charge			15		nC

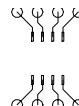
**Notes:** 1.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a)  $50^\circ\text{C}/\text{W}$  when mounted on a  $1\text{ in}^2$  pad of 2 oz copper



b)  $105^\circ\text{C}/\text{W}$  when mounted on a  $.04\text{ in}^2$  pad of 2 oz copper



c)  $125^\circ\text{C}/\text{W}$  when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width  $< 300\mu\text{s}$ , Duty Cycle  $< 2.0\%$

3. See "SyncFET Schottky body diode characteristics" below.

4. FDS6670AS\_NL is a lead free product. The FDS6670AS\_NL marking will appear on the reel label.

## Typical Characteristics

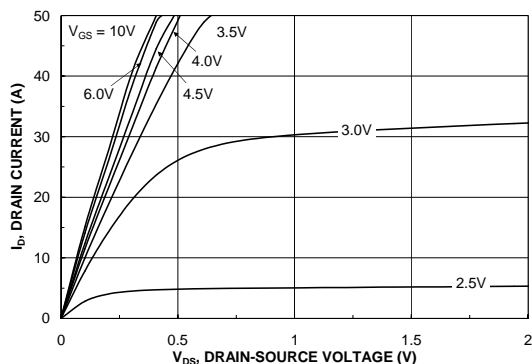


Figure 1. On-Region Characteristics.

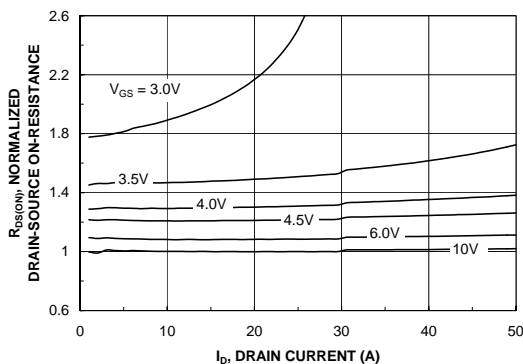


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

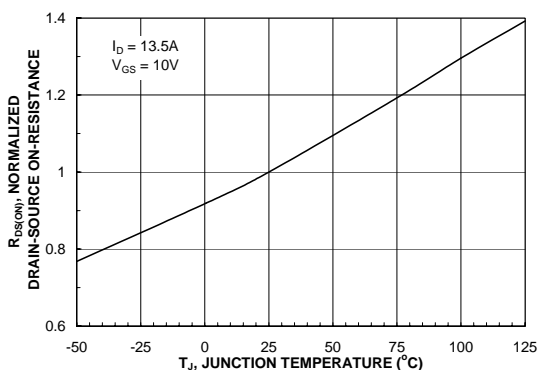


Figure 3. On-Resistance Variation with Temperature.

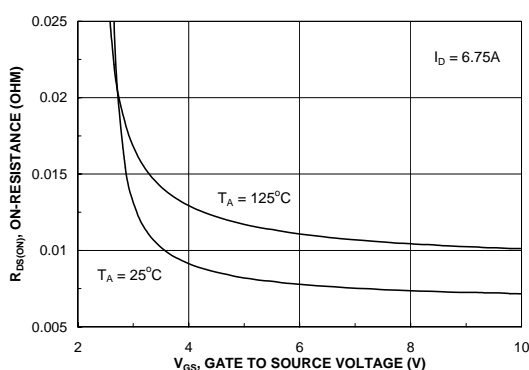


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

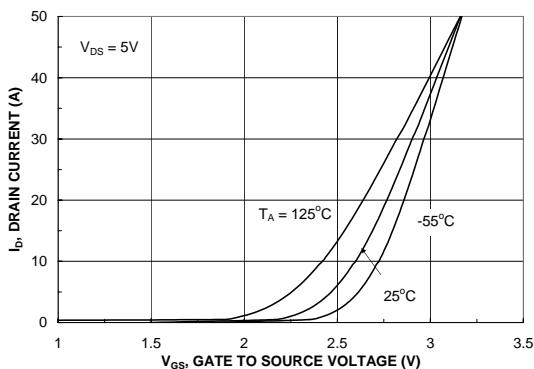


Figure 5. Transfer Characteristics.

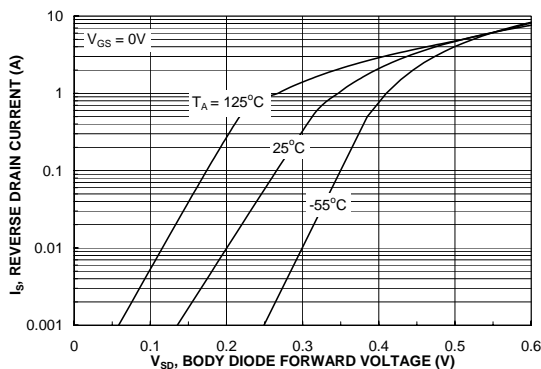
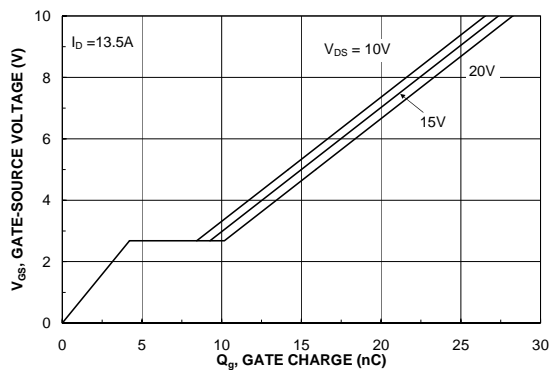
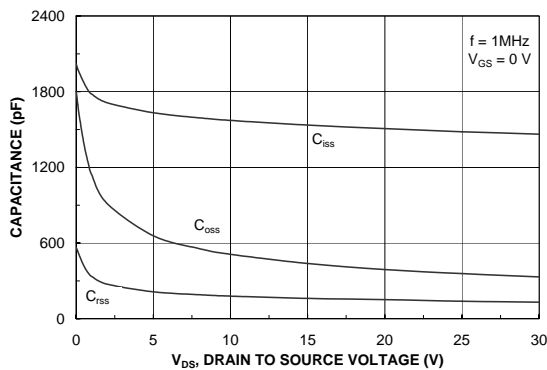


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

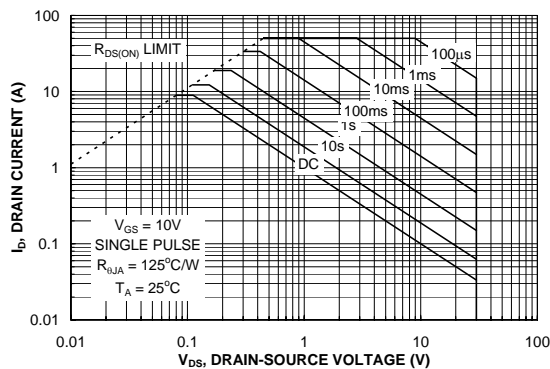
**Typical Characteristics** (continued)



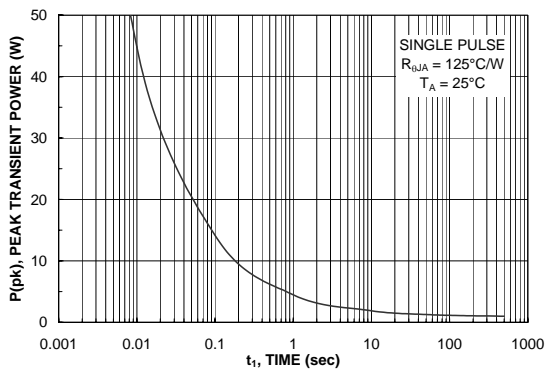
**Figure 7. Gate Charge Characteristics.**



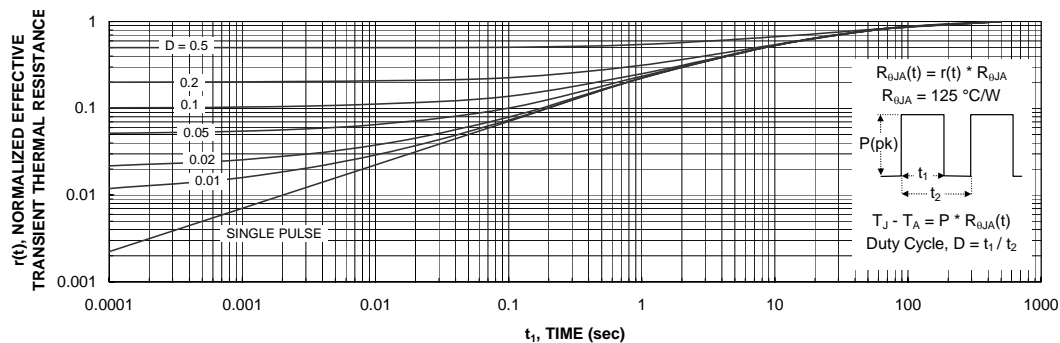
**Figure 8. Capacitance Characteristics.**



**Figure 9. Maximum Safe Operating Area.**



**Figure 10. Single Pulse Maximum Power Dissipation.**



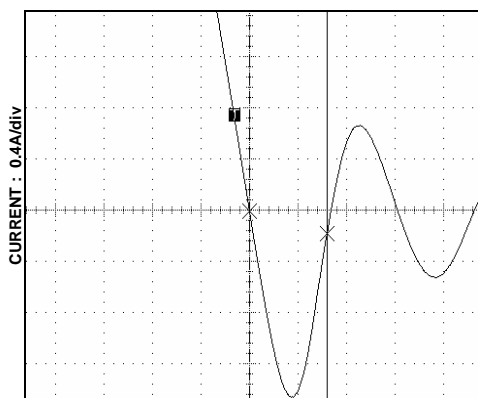
**Figure 11. Transient Thermal Response Curve.**

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

## Typical Characteristics (continued)

### SyncFET Schottky Body Diode Characteristics

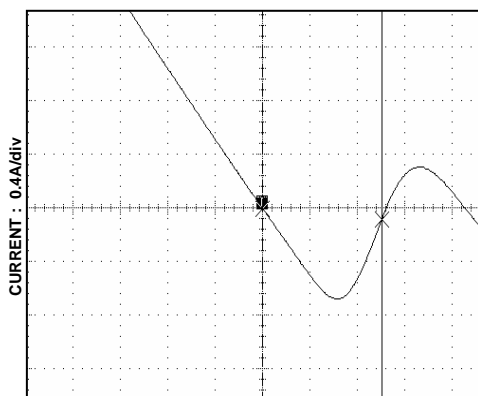
Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 12 shows the reverse recovery characteristic of the FDS6670AS.



TIME : 12.5ns/div

**Figure 12. FDS6670AS SyncFET body diode reverse recovery characteristic.**

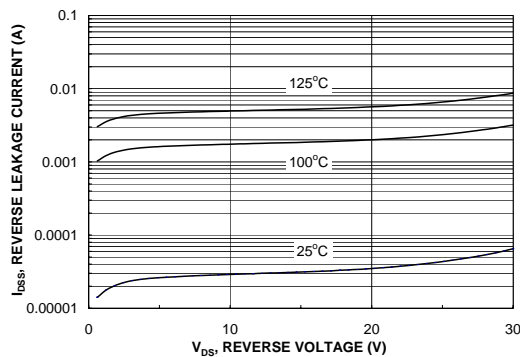
For comparison purposes, Figure 13 shows the reverse recovery characteristics of the body diode of an equivalent size MOSFET produced without SyncFET (FDS6670A).



TIME : 12.5ns/div

**Figure 13. Non-SyncFET (FDS6670A) body diode reverse recovery characteristic.**

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.



**Figure 14. SyncFET body diode reverse leakage versus drain-source voltage and temperature.**

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FACT™	ImpliedDisconnect™	OCX™	RapidConfigure™	TruTranslation™
FACT Quiet Series™		OCXPro™	RapidConnect™	UHC™
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## PRODUCT STATUS DEFINITIONS

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Datasheet Identification	Product Status	Definition
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Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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